- 16. (Original) The structure as recited in claim 14, wherein a bond-line thickness of the second adhesive layer is determined by a pair of ridges extending outward from substantially planar sidewall surfaces of the groove of the other joining member.
- 17. (Original) The structure as recited in claim 14, wherein the first and second adhesive layers comprise epoxy adhesive materials.

REMARKS/ARGUMENTS

Claim 1 was rejected in light of the prior art and claims 14-17 were allowed.

Claims 14-17 should remain in condition for allowance.

Other claims have been cancelled without disclaimer of the subject matter of the claims.

In closing, I wish to express my appreciation for your kind consideration and helpful comments.

Respectfully submitted,

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I hereby certify that this correspondence is being sent via facsimile to the Commissioner for Patents at 571-273-8300 on 10-25-0 date of deposit.

Signature: